Kui Xiao

List of Publications by Year in descending order

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567281 501196 41 860 15 28 citations h-index g-index papers 42 42 42 566 docs citations citing authors all docs times ranked

#	Article	IF	CITATIONS
1	Atmospheric corrosion of field-exposed AZ31 magnesium in a tropical marine environment. Corrosion Science, 2013, 76, 243-256.	6.6	137
2	In situ Raman spectroscopy study of corrosion products on the surface of carbon steel in solution containing Clâ ⁻² and <mml:math altimg="si1.gif" overflow="scroll" xmlns:mml="http://www.w3.org/1998/Math/MathML"><mml:mrow><mml:msubsup><mml:mrow><mml:mtext>SO</mml:mtext></mml:mrow><mm 18,="" 1981-1989.<="" 2011,="" analysis,="" engineering="" failure="" td=""><td>l:mfow><r< td=""><td>mml:mn>4</td></r<></td></mm></mml:msubsup></mml:mrow></mml:math>	l:mfow> <r< td=""><td>mml:mn>4</td></r<>	mml:mn>4
3	Corrosion products and formation mechanism during initial stage of atmospheric corrosion of carbon steel. Journal of Iron and Steel Research International, 2008, 15, 42-48.	2.8	84
4	Electrochemical migration, whisker formation, and corrosion behavior of printed circuit board under wet H2S environment. Electrochimica Acta, 2013, 114, 363-371.	5.2	61
5	Atmospheric corrosion factors of printed circuit boards in a dry-heat desert environment: Salty dust and diurnal temperature difference. Chemical Engineering Journal, 2018, 336, 92-101.	12.7	36
6	The corrosion behavior of PCB-ImAg in industry polluted marine atmosphere environment. Materials and Design, 2017, 115, 404-414.	7.0	29
7	Electrochemical Migration Behavior of Copper-Clad Laminate and Electroless Nickel/Immersion Gold Printed Circuit Boards under Thin Electrolyte Layers. Materials, 2017, 10, 137.	2.9	27
8	Surface failure analysis of a field-exposed copper-clad plate in a marine environment with industrial pollution. Applied Surface Science, 2017, 399, 608-616.	6.1	26
9	Effects of mould on electrochemical migration behaviour of immersion silver finished printed circuit board. Bioelectrochemistry, 2018, 119, 203-210.	4.6	25
10	Surface analysis of silver-plated circuit boards in a salt-spray environment. Journal of Alloys and Compounds, 2016, 688, 301-312.	5.5	24
11	Atmospheric corrosion behavior of low-alloy steels in a tropical marine environment. Journal of Iron and Steel Research International, 2019, 26, 1315-1328.	2.8	23
12	Surface failure mechanism of PCB-ENIG in typical outdoor atmospheric environments. Materials Research Bulletin, 2017, 91, 179-188.	5.2	22
13	Copper corrosion in hot and dry atmosphere environment in Turpan, China. Transactions of Nonferrous Metals Society of China, 2016, 26, 1721-1728.	4.2	21
14	Effect of Manufacturing Parameters on the Mechanical and Corrosion Behavior of Selective Laserâ€Melted 15â€5PH Stainless Steel. Steel Research International, 2020, 91, 1900447.	1.8	21
15	Effect of Concentrations of Fe2+ and Fe3+ on the Corrosion Behavior of Carbon Steel in Clâ [^] and SO42â [^] Aqueous Environments. Metals and Materials International, 2021, 27, 2623-2633.	3.4	21
16	In situ investigation of atmospheric corrosion behavior of PCB-ENIG under adsorbed thin electrolyte layer. Transactions of Nonferrous Metals Society of China, 2016, 26, 1146-1154.	4.2	17
17	Effect of iron ion diffusion on the corrosion behavior of carbon steels in soil environment. RSC Advances, 2018, 8, 40544-40553.	3.6	15
18	EFFECT OF MOLD ON CORROSION BEHAVIOR OF PRINTED CIRCUIT BOARD-COPPER AND ENIG FINISHED. Jinshu Xuebao/Acta Metallurgica Sinica, 2012, 48, 687.	0.3	14

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19	Electrochemical migration behavior and mechanism of PCB-ImAg and PCB-HASL under adsorbed thin liquid films. Transactions of Nonferrous Metals Society of China, 2015, 25, 2446-2457.	4.2	13
20	Electrochemical migration failure mechanism and dendrite composition characteristics of Sn96.5Ag3.0Cu0.5 alloy in thin electrolyte films. Journal of Materials Science: Materials in Electronics, 2019, 30, 6575-6582.	2.2	13
21	Initial Corrosion Behavior and Mechanism of PCB–HASL in Typical Outdoor Environments in China. Journal of Electronic Materials, 2015, 44, 4405-4417.	2.2	10
22	Corrosion Behavior of Silver-Plated Circuit Boards in a Simulated Marine Environment with Industrial Pollution. Materials, 2017, 10, 762.	2.9	10
23	Corrosion Acceleration of Printed Circuit Boards With an Immersion Silver Layer Exposed to Bacillus cereus in an Aerobic Medium. Frontiers in Microbiology, 2019, 10, 1493.	3.5	10
24	Initial corrosion behavior of a copper-clad plate in typical outdoor atmospheric environments. Electronic Materials Letters, 2016, 12, 163-170.	2.2	9
25	Role of mold in electrochemical migration of copper-clad laminate and electroless nickel/immersion gold printed circuit boards. Materials Letters, 2018, 210, 283-286.	2.6	9
26	Effect of static magnetic field on mold corrosion of printed circuit boards. Bioelectrochemistry, 2020, 131, 107394.	4.6	9
27	Influence of atmospheric particulates on initial corrosion behavior of printed circuit board in pollution environments. Applied Surface Science, 2019, 467-468, 889-901.	6.1	8
28	Microporous corrosion behavior of gold-plated printed circuit boards in an atmospheric environment with high salinity. Journal of Materials Science: Materials in Electronics, 2018, 29, 8877-8885.	2.2	6
29	Microstructure and Grain Boundary Corrosion Mechanism of Pearlitic Material. Journal of Materials Engineering and Performance, 2022, 31, 483-494.	2.5	6
30	Localized electrochemical impedance spectroscopy study on the corrosion behavior of Fe-Cr alloy in the solution with Clâ^' and SO4 2â^'. Journal Wuhan University of Technology, Materials Science Edition, 2012, 27, 27-32.	1.0	5
31	The influence of <i>Bacillus subtilis</i> on tin-coated copper in an aqueous environment. RSC Advances, 2018, 8, 4671-4679.	3.6	5
32	Co-enhancing the Mechanical Property and Corrosion Resistance of Selective Laser Melted High-Strength Stainless Steel via Cryogenic Treatment. Journal of Materials Engineering and Performance, 2020, 29, 7052-7062.	2.5	5
33	Unexpected Stress Corrosion Cracking Improvement Achieved by Recrystallized Layer in Al-Zn-Mg Alloy. Journal of Materials Engineering and Performance, 2021, 30, 6258-6268.	2.5	5
34	A novel extraction method of device parameters for thin-film transistors (TFTs). Physics Letters, Section A: General, Atomic and Solid State Physics, 2021, 403, 127386.	2.1	5
35	Image Deep Learning Assisted Prediction of Mechanical and Corrosion Behavior for Al-Zn-Mg Alloys. IEEE Access, 2022, 10, 35620-35631.	4.2	4
36	Comparative study on extraction methods of threshold voltage for thinâ€film transistors. Journal of the Society for Information Display, 2019, 27, 816-821.	2.1	2

#	Article	lF	CITATIONS
37	The Passivity of Pure Nickel in Alkaline Solution under Different Temperatures: Electrochemical Verification and First-Principles Calculation. Journal of Materials Engineering and Performance, 2021, 30, 1737-1747.	2.5	2
38	Correlation between indoor and outdoor corrosion tests for coal train body steel in a coal medium environment. Journal of Iron and Steel Research International, 0 , 1 .	2.8	2
39	Microbiologically Influenced Corrosion of AA 6061 with Bacillus Species in an Environment Containing an Organic Nitrogen Source. Journal of Materials Engineering and Performance, 2022, 31, 1870-1880.	2.5	1
40	Effect of Fungus, Aspergillus sp. F1-1, on the corrosion behavior of PCB-HASL in humid atmospheric environment. Surface Topography: Metrology and Properties, 2022, 10, 015022.	1.6	1
41	Electrochemical migration behavior of moldy printed circuit boards in a 10 mT magnetic field. RSC Advances, 2021, 11, 28178-28188.	3.6	0